Product data sheet

1. General description

Dual Silicon Carbide Schottky diode in a TO247-3L plastic package, designed for high frequency switched-mode power supplies.



2. Features and benefits

- · Highly stable switching performance
- High forward surge capability I_{FSM}
- Extremely fast reverse recovery time
- Superior in efficiency to Silicon Diode alternatives
- · Reduced losses in associated MOSFET
- Reduced EMI
- · Reduced cooling requirements
- RoHS compliant
- High junction operating temperature capability $(T_{j(max)} = 175 \text{ °C})$

3. Applications

- · Power factor correction
- Telecom / Server SMPS
- UPS
- PV inverter
- PC Silverbox
- LED / OLED TV
- Motor Drives

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Notes	Values		Unit	
Absolute	maximum rating						
V_{RRM}	repetitive peak reverse voltage				1200		V
I _{O(AV)}	limiting average forward current	δ = 0.5; square-wave pulse; $T_{mb} \le$ 126 °C; both diodes conducting; Fig. 1; Fig. 2; Fig. 3		30		А	
T _j	junction temperature			-55 to 175		°C	
Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
Static ch	aracteristics						
V _F	forward voltage	I _F = 15 A; T _j = 25 °C; per diode; <u>Fig. 5</u>		-	1.42	1.60	V
		I _F = 15 A; T _j = 150 °C; per diode; <u>Fig. 5</u>		-	1.90	2.30	V
		$I_F = 15 \text{ A}; T_j = 175 °C; \text{ per diode}; Fig. 5$		-	2.00	2.50	V
Dynamic	characteristics		1				
Q_r	recovered charge	$I_F = 15 \text{ A}$; $dI_F/dt = 500 \text{ A/µs}$; $V_R = 400 \text{ V}$; $T_i = 25 \text{ °C}$; per diode; Fig. 7		-	36	-	nC

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	A1	anode		
2	K	cathode		A1
3	A2	anode		K
mb	mb	mounting base; connected to cathode	1 2 3	sym125

6. Ordering information

Table 3. Ordering information

Type number	Package	Orderable part number	Packing	Small packing	Package	Package
	name		method	quantity	version	issue date
WNSC2D301200CW	TO247	WNSC2D301200CW6Q	Tube	30	SOT429	25-Mar-2013

7. Marking

Table 4. Marking codes

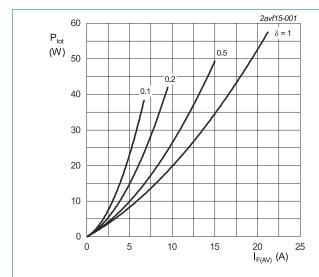
Type number	Marking codes
WNSC2D301200CW	WNSC2D 301200CW

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Notes	Values	Unit
V_{RRM}	repetitive peak reverse voltage			1200	V
V_{RWM}	crest working reverse voltage			1200	V
V_R	reverse voltage	DC		1200	V
I _{O(AV)}	limiting average forward current	δ = 0.5; square-wave pulse; T _{mb} ≤ 126 °C; both diodes conducting; <u>Fig. 1</u> ; <u>Fig. 2</u> ; <u>Fig. 3</u>		30	А
I _{FRM}	repetitive peak forward current	δ = 0.5; t _p = 25 μs; T _{mb} ≤ 131 °C; square-wave pulse; per diode		30	А
I _{FSM}	non-repetitive peak forward current	t_p = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse; per diode		140	А
		t_p = 10 μ s; $T_{j(init)}$ = 25 °C; square-wave pulse; per diode		900	А
I ² t	I ² t for fusing	sine-wave pulse; $T_{j(init)}$ = 25 °C; t_p = 10 ms		98	A ² s
T _{stg}	storage temperature			-55 to 175	°C
T _j	junction temperature			-55 to 175	°C



 $I_{F(AV)} = I_{F(RMS)} \times \sqrt{\delta}$ $V_o = 1.321 \text{ V; } R_s = 0.0655 \Omega$

Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values; per diode

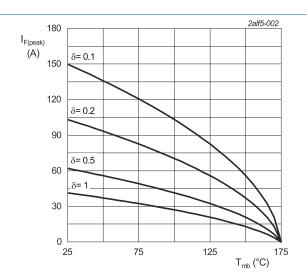
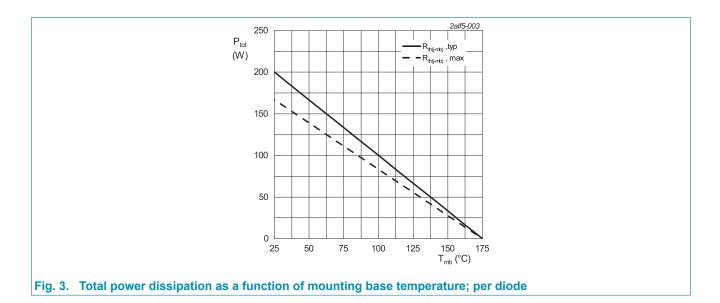


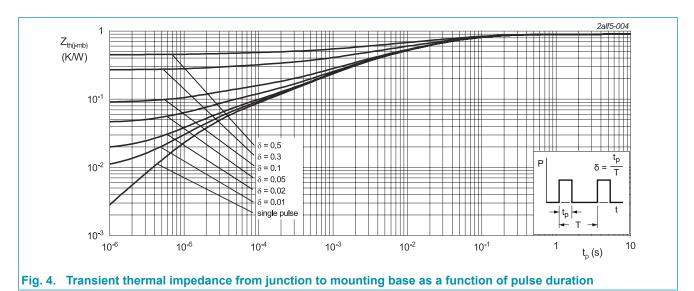
Fig. 2. Current derating as a function of mounting base temperature; per diode



9. Thermal characteristics

Table 6. Thermal characteristics

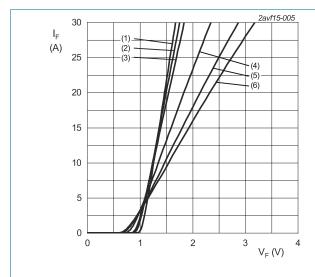
Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
R _{th(j-mb)}	thermal resistance	per diode; Fig. 4		-	0.75	0.9	K/W
	from junction to mounting base	both diodes conducting		-	0.38	0.5	K/W
R _{th(j-a)}	thermal resistance from junction to ambient free air	in free air		-	40	-	K/W



10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
Static cha	aracteristics		'				
V _F	forward current	I _F = 15 A; T _j = 25 °C; per diode; <u>Fig. 5</u>		-	1.42	1.60	V
		I _F = 15 A; T _j = 150 °C; per diode; <u>Fig. 5</u>		-	1.90	2.30	V
		I _F = 15 A; T _j = 175 °C; per diode; <u>Fig. 5</u>		-	2.00	2.50	V
I _R	reverse current	V _R = 1200 V; T _j = 25 °C; per diode; <u>Fig. 6</u>		-	1	75	μΑ
		V _R = 1200 V; T _j = 175 °C; per diode; <u>Fig. 6</u>		-	25	750	μΑ
Dynamic	characteristics						
Q _r	recovered charge	$I_F = 15 \text{ A}$; $V_R = 400 \text{ V}$; $dI_F/dt = 500 \text{ A}/\mu\text{s}$; $T_j = 25 \text{ °C}$; per diode; Fig. 7		-	36	-	nC
C _d	diode capacitance	$f = 1 \text{ MHz}$; $V_R = 1 \text{ V}$; $T_j = 25 \text{ °C}$; per diode		-	800	-	pF
		f = 1 MHz; V _R = 400 V; T _j = 25 °C; per diode		-	66	-	pF
		f = 1 MHz; V _R = 800 V; T _j = 25 °C; per diode		-	48	-	pF
E _{as}	non-repetitive avalanche energy	I_R = 4.7 A; L = 10 mH; $T_{j(init)}$ = 25 °C; per diode		110	-	-	mJ



 V_o = 1.321 V; R_s = 0.0655 Ω

(1) $T_j = -55$ °C; typical values

(2) T_j = 0 °C; typical values

(3) T_i = 25 °C; typical values

(4) $T_j = 100 \, ^{\circ}\text{C}$; typical values

(5) $T_j = 150$ °C; typical values

(6) T_i = 175 °C; typical values

Fig. 5. Forward current as a function of forward voltage; typical values; per diode

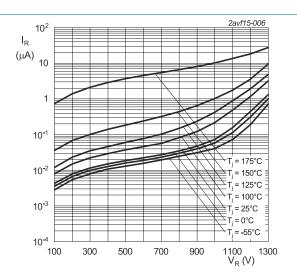


Fig. 6. Reverse leakage current as a function of reverse voltage; typical value; per diode

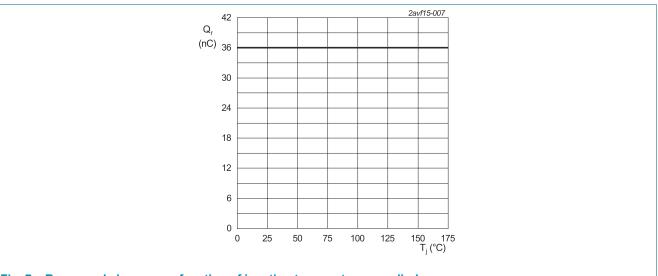
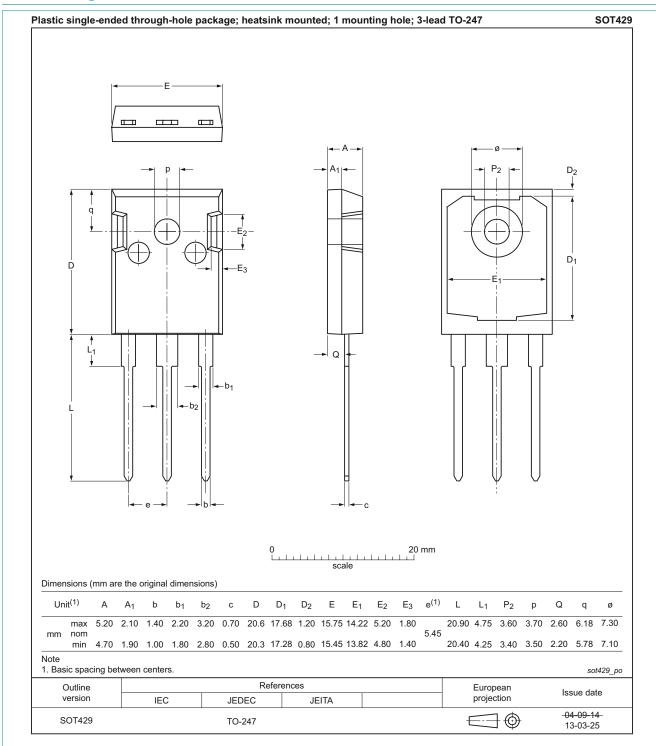


Fig. 7. Recovered charge as a function of junction temperature; per diode

11. Package outline



12. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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- [2] The term 'short data sheet' is explained in section "Definitions".
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